





**Two-terminal SMT-miniature-housing of semiconductor device and process of manufacturing the same.**

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- **international:** H01L31/0203; H01L33/00  
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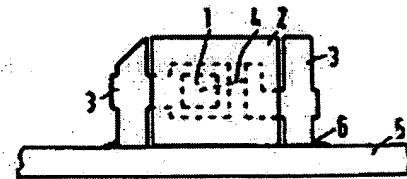
 EP0646971 (A3)  
 EP0646971 (B1)

**Cited documents:**

 DE2829260  
 JP4128811

**Abstract of EP0646971**

A two-terminal miniature SMT (SMD) housing using lead-frame technology for semiconductor components, in which a semiconductor chip (1) is mounted on a lead frame part and is connected to another lead frame part, which lead frame parts are led out as soldered connections (3) from a housing (2) in which the chip (1) is encapsulated, is intended to be rationally producible without a trimming and shaping process and to be reliably sealed and further miniaturisable. The soldered connections (3) extend, as punched parts of the lead frame, laterally separated from opposite housing side walls, at least as far as the housing bottom forming the component mounting surface, the chip mounting surface and the component mounting surface forming a right angle between them.

**FIG 1**

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